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#### 100V COMPLEMENTARY MEDIUM POWER TRANSISTOR IN SM-8

#### **Features**

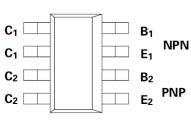
- NPN Transistor
  - BV<sub>CEO</sub> > 100
  - I<sub>C</sub> = 2A High Continuous Current
  - Low Saturation Voltage V<sub>CE(sat)</sub> < 300mV @ 1A</li>
- PNP Transistor
  - BV<sub>CEO</sub> > -100V
  - I<sub>C</sub> = -2A High Continuous Current
  - Low Saturation Voltage V<sub>CE(sat)</sub> < -300mV @ -1A
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

#### **Mechanical Data**

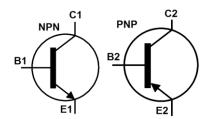
- Case: SM-8 (8 LEAD SOT223)
- Case Material: Molded Plastic, "Green" Molding Compound;
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads. Solderable per MIL-STD-202. Method 208 (3)
- Weight: 0.117 grams (Approximate)







Top View Pin Out



Equivalent Circuit

#### **Ordering Information** (Note 4)

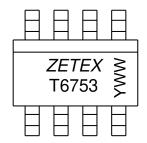
Part Number	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
ZDT6753TA	T6753	7	12	1,000
ZDT6753TC	T6753	13	12	4,000

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

# Marking Information

SM-8



T6753 = Product Type Marking Code YWW = Date Code Marking Y or  $\overline{Y}$  = Last Digit of Year (ex: 5= 2015) WW or  $\overline{W}W$  = Week Code (01~53)



#### Absolute Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	NPN	PNP	Unit
Collector-Base Voltage	V <sub>CBO</sub>	120	-120	V
Collector-Emitter Voltage	V <sub>CEO</sub>	100	-100	V
Emitter-Base Voltage	V <sub>EBO</sub>	7	-7	V
Continuous Collector Current	Ic	2	-2	Α
Peak Pulse Current (Note 5)	Ісм	6	-6	Α

## Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Collector Power Dissipation	(Note 5)	D	2.25	W
Collector Fower Dissipation	(Note 6)	P <sub>D</sub>	2.75	VV
Thermal Resistance, Junction to Ambient	(Note 5)	В	55.6	°C/W
Thermal nesistance, Junction to Ambient	(Note 6)	- R <sub>θJA</sub>	45.5	C/VV
Thermal Resistance, Junction to Leads (Note 7)		$R_{ heta JL}$	30.7	°C/W
Operating and Storage Temperature Range	$T_{J,}T_{STG}$	-55 to +150	°C	

#### ESD Ratings (Note 8)

Characteristic	Symbol	Value	Unit	JEDEC Class	
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A	
Electrostatic Discharge - Machine Model	ESD MM	400	V	С	

Notes:

- 5. For a device with any single die active and mounted with the collector lead on 25mm x 25mm 2oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in steady-state.
- 6. Same as Note 5, except both die are active and equally sharing power.
- 7. Thermal resistance from junction to solder-point (at the end of the collector lead).

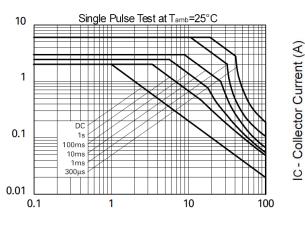
  8. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

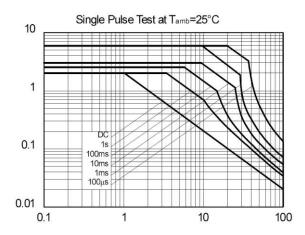




## **Thermal Characteristics and Derating Information**



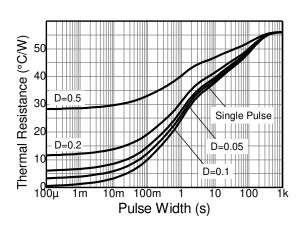


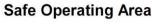


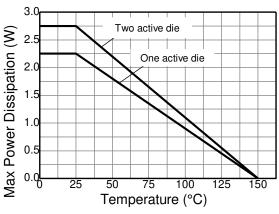
VCE - Collector Emitter Voltage (V)

VCE - Collector Emitter Voltage (V)

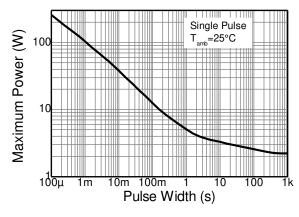
### Safe Operating Area







#### **Transient Thermal Impedance**



**Derating Curve** 

**Pulse Power Dissipation** 



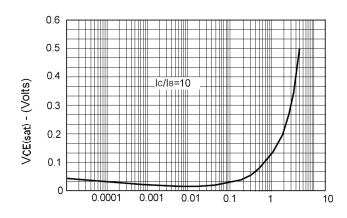
# NPN - Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	$BV_{CBO}$	120	_	_	V	$I_C = 100\mu A$
Collector-Emitter Breakdown Voltage (Note 9)	$BV_CEO$	100	_	_	V	$I_C = 10mA$
Emitter-Base Breakdown Voltage	BV <sub>EBO</sub>	7	_	_	V	$I_E = 100 \mu A$
Collector Cut-Off Current	1	_	< 1	0.1	μΑ	V <sub>CB</sub> = 100V
Collector Cut-On Current	I <sub>CBO</sub>	_	_	10	μΑ	$V_{CB} = 100V, T_A = +125^{\circ}C$
Emitter Cut-Off Current	I <sub>EBO</sub>	_	< 1	0.1	μΑ	$V_{EB} = 5.6V$
		70	200	_		$I_C = 50$ mA, $V_{CE} = 2V$
DC Current Transfer Static Patic (Note 0)		100	200	300		I <sub>C</sub> = 500mA, V <sub>CE</sub> = 2V
DC Current Transfer Static Ratio (Note 9)	h <sub>FE</sub>	55	110	_	_	$I_C = 1A$ , $V_{CE} = 2V$
		25	55	_		$I_C = 2A$ , $V_{CE} = 2V$
Collector Emitter Seturation Valtage (Note 0)	V <sub>CE(sat)</sub>	_	0.13	0.30	V	$I_C = 1A$ , $I_B = 100mA$
Collector-Emitter Saturation Voltage (Note 9)		_	0.23	0.50		$I_C = 2A$ , $I_B = 200mA$
Base-Emitter Saturation Voltage (Note 9)	V <sub>BE(sat)</sub>	_	0.9	1.25	V	I <sub>C</sub> = 1A, I <sub>B</sub> = 100mA
Base-Emitter Turn-on Voltage (Note 9)	V <sub>BE(on)</sub>	_	0.8	1.0	V	$I_C = 1A$ , $V_{CE} = 2V$
Transitional Frequency	f <sub>T</sub>	140	175	_	MHz	I <sub>C</sub> = 100mA, V <sub>CE</sub> = 5V, f = 100MHz
Output Capacitance	C <sub>obo</sub>	_	_	30	pF	V <sub>CB</sub> = 10V, f = 1MHz
Cuitabing Time	t <sub>on</sub>	_	80	_	Ns	V <sub>CC</sub> = 10V, I <sub>C</sub> = 500mA,
Switching Time	t <sub>off</sub>	_	1200	_	ns	$I_{B1} = -I_{B2} = 50 \text{mA}$

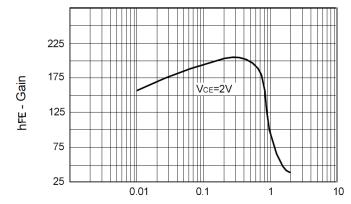
Note: 9. Measured under pulsed conditions. Pulse width  $\leq$  300 $\mu$ s. Duty cycle  $\leq$  2%.



# NPN - Typical Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)



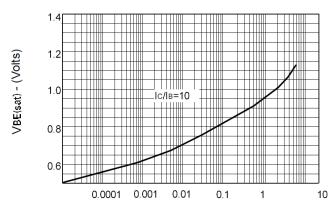
Ic - Collector Current (Amps)



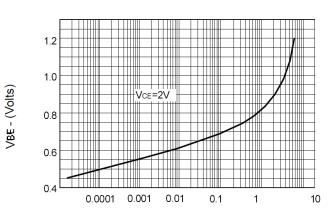
Ic - Collector Current (Amps)

#### hfe v IC

#### VCE(sat) v IC



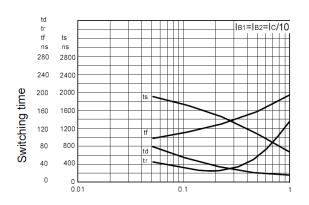
Ic - Collector Current (Amps)



Ic - Collector Current (Amps)

#### VBE(on) v IC

#### VBE(sat) v IC



Ic - Collector Current (Amps)

#### **Switching Speeds**



# PNP - Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

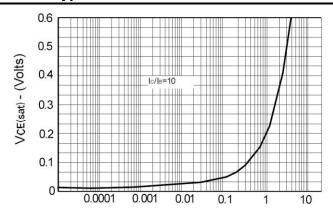
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	$BV_CBO$	-120	_	_	V	$I_C = -100 \mu A$
Collector-Emitter Breakdown Voltage (Note 9)	BV <sub>CEO</sub>	-100	_	_	V	I <sub>C</sub> = -10mA
Emitter-Base Breakdown Voltage	$BV_{EBO}$	-7	_	_	V	$I_E = -100 \mu A$
Collector Cut-Off Current		_	< 1	-0.1	μΑ	V <sub>CB</sub> = -100V
Collector Gut-Oil Gurrent	I <sub>CBO</sub>	_	_	-10	μΑ	V <sub>CB</sub> = -100V, T <sub>A</sub> = +125°C
Emitter Cut-Off Current	I <sub>EBO</sub>	_	< 1	-0.1	μΑ	V <sub>EB</sub> = -5.6V
		70	200	_		$I_C = -50 \text{mA}, V_{CE} = -2 \text{V}$
DC Current Transfer Static Datic (Note 9)	L	100	200	300	_	$I_C = -500 \text{mA}, V_{CE} = -2V$
DC Current Transfer Static Ratio (Note 8)	h <sub>FE</sub>	55	170	_		$I_C = -1A$ , $V_{CE} = -2V$
		25	55	_		$I_C = -2A$ , $V_{CE} = -2V$
0	V <sub>CE(sat)</sub>	_	-0.17	-0.30	V	$I_C = -1A$ , $I_B = -100mA$
Collector-Emitter Saturation Voltage (Note 9)		_	-0.30	-0.50		$I_C = -2A$ , $I_B = -200mA$
Base-Emitter Saturation Voltage (Note 9)	$V_{BE(sat)}$	_	-0.90	-1.25	V	$I_C = -1A$ , $I_B = -100mA$
Base-Emitter Turn-On Voltage (Note 9)	V <sub>BE(on)</sub>	_	-0.80	-1.0	V	$I_C = -1A$ , $V_{CE} = -2V$
Transitional Frequency	f⊤	100	140	_	MHz	$I_C = -100 \text{mA}, V_{CE} = -5 \text{V},$ f = 100 MHz
Output Capacitance	C <sub>obo</sub>	_	_	30	pF	$V_{CB} = -10V, f = 1MHz,$
Suitables Time	t <sub>on</sub>	35	35		ns	V <sub>CC</sub> = -10V, I <sub>C</sub> = -500mA,
Switching Time	t <sub>off</sub>	_	600		ns	$I_{B1} = -I_{B2} = -50 \text{mA}$

Note:

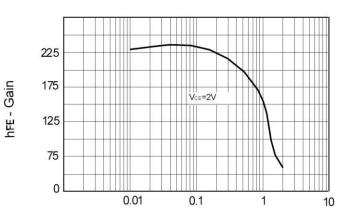
9. Measured under pulsed conditions. Pulse width  $\leq$  300 $\mu$ s. Duty cycle  $\leq$  2%.



# PNP - Typical Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

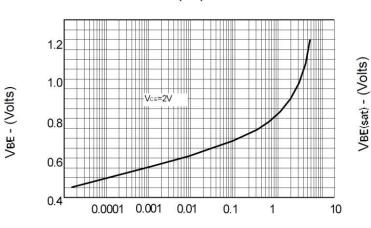


Ic - Collector Current (Amps)



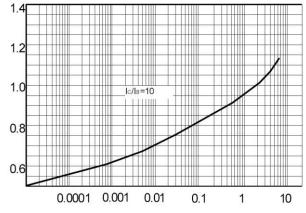
Ic - Collector Current (Amps)

## VCE(sat) v IC



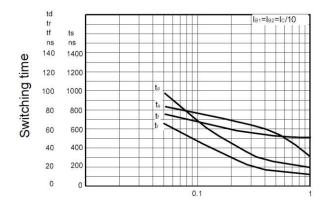
Ic - Collector Current (Amps)

# hfe v lc



Ic - Collector Current (Amps)

#### VBE(on) V IC



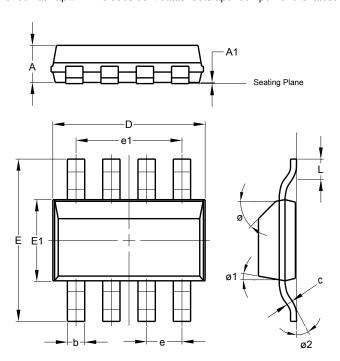
Ic - Collector Current (Amps)

# **Switching Speeds**



# **Package Outline Dimensions**

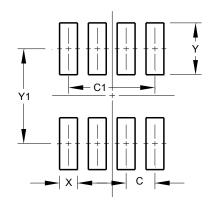
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



SM-8					
Dim	Min Max Typ				
Α		1.70	1.60		
<b>A</b> 1	0.02	0.10	0.04		
b	0.70	0.90	0.80		
С	0.24	0.32	0.28		
D	6.30	6.70	6.60		
е	1.53 REF				
e1	4.59 REF				
Е	6.70 7.30 7.00				
E1	3.30	3.70	3.50		
L	0.75	1.00	0.90		
Ø	45°				
Ø1		15°			
Ø2			10°		
All Dimensions in mm					

# **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)			
С	1.52			
C1	4.6			
X	0.95			
Υ	2.80			
Y1	6.80			

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device terminals and PCB tracking.





March 2015

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